

## Technical Requirements for the Education Instruments Program

### 1. Manufacturing of Printed Circuit Boards for The Radiation Education Equipment Kit 2018

*Table 1: Requirements for Printed Circuit Boards*

| Circuit   | Estimated board size (L x W x T) mm | Special Remarks   | Qty. |
|---|-------------------------------------|---|------|
| Portable Surveymeter Main Board   | 69 x 70 x 1.2                       | <b>No. of Layers:</b> 2<br><b>Copper Density:</b> 1 oz. per sq. ft.<br><b>Solder Mask:</b> Red<br><b>Type of component mounting:</b> SMD (95%) & THT (5%) hybrid    | 100  |
| GM Counter – Front Panel  | 150 x 70 x 1.6                      | <b>No. of Layers:</b> 2<br><b>Copper Density:</b> 1 oz. per sq. ft.<br><b>Solder Mask:</b> Red<br><b>Type of component mounting:</b> SMT (40%) & THT (60%) hybrid   | 100  |
| GM Counter – Control Panel  | 80 x 60 x 1.6                       | <b>No. of Layers:</b> 2<br><b>Copper Density:</b> 1 oz. per sq. ft.<br><b>Solder Mask:</b> Blue<br><b>Type of component mounting:</b> SMT (95%) & THT (5%) hybrid   | 100  |
| GM Counter – Power Panel  | 90 x 45 x 1.6                       | <b>No. of Layers:</b> 2<br><b>Copper Density:</b> 1 oz. per sq. ft.<br><b>Solder Mask:</b> Green<br><b>Type of component mounting:</b> SMT (70%) & THT (30%) hybrid | 100  |
| GM Counter – Indicator Panel  | 60 x 30 x 1.6                       | <b>No. of Layers:</b> 2<br><b>Copper Density:</b> 1 oz. per sq. ft.<br><b>Solder Mask:</b> Green<br><b>Type of component mounting:</b> SMT (95%) & THT (5%) hybrid  | 100  |
| <ul style="list-style-type: none"> <li>• The computer aided manufacturing (CAM) files (Gerber file format) for each design will be submitted to the selected bidder. Original designs will not be disclosed.</li> <li>• The bidder must be responsible and must adhere to the ownership of the designs and intellectual property rights.</li> <li>• The designs may have irregular shapes.</li> </ul> |                                     |   |      |